

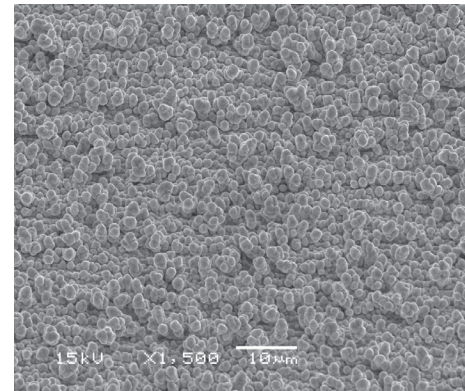
High temperature stability, reverse treat, electrodeposited copper foil.

Applications:

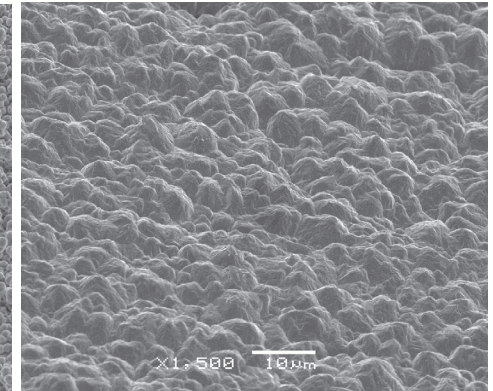
- PCB inner layers

Features:

- IPC Grade III
- Treatment on drum side of foil
- High temperature lamination compatible



Treated Drum Side
0.5 Oz. 18µm (1500x)



Untreated Matte Side
0.5 Oz. 18µm (1500x)

Typical Values:

| Attribute | | Unit | Value | | | | Reference |
|---------------------------------------|------------|-----------------------|-------|------|------|------|---|
| Thickness Designation | | | H | 1 | 2 | 3 | IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12 |
| Nominal Thickness | | µm | 18 | 35 | 70 | 103 | |
| | | oz. | 1/2 | 1 | 2 | 3 | |
| Area Weight | | g/m ² | 152.5 | 305 | 610 | 915 | |
| | | g/254 in ² | 25 | 50 | 100 | 150 | |
| | | oz./ft ² | 0.5 | 1 | 2 | 3 | |
| Roughness | Drum Side | µm | 4.1 | | | | IPC-TM-650-2.2.17 |
| | | µ" | 160 | | | | |
| | Matte Side | µm | 4.5 | 5.7 | 8.9 | 15.0 | |
| | | µ" | 175 | 225 | 350 | 590 | |
| Tensile | Ambient | Kg/mm ² | 42.2 | 38.7 | 36.9 | 34.4 | IPC-TM-650-2.4.18 |
| | | Kpsi | 60 | 55 | 52.5 | 48.9 | |
| | 180°C | Kg/mm ² | 21 | | | | |
| | | Kpsi | 30 | | | | |
| Elongation | Ambient | % | 8 | 15 | 20 | 26 | |
| | 180°C | % | 8 | | | 7.2 | |
| Peel Strength* (Drum/Treated Side) | Cond. B | Kg/cm | 0.98 | 1.16 | 1.25 | 1.20 | IPC-TM-650-2.4.8 |
| | | Lbs/in | 5.5 | 6.5 | 7.0 | 6.7 | |

* Peel strength measured on 170°C Tg Epoxy

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